

LC²MOS Precision Mini-DIP Analog Switch

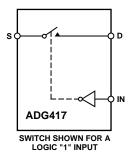
ADG417

FEATURES

44 V Supply Maximum Ratings V_{SS} to V_{DD} Analog Signal Range Low On Resistance (<35 Ω) Ultralow Power Dissipation (<35 μ W) Fast Switching Times t_{ON} (160 ns max) t_{OFF} (100 ns max) Break-Before-Make Switching Action Plug-In Replacement for DG417

APPLICATIONS Precision Test Equipment Precision Instrumentation Battery Powered Systems Sample Hold Systems

FUNCTIONAL BLOCK DIAGRAM



GENERAL DESCRIPTION

The ADG417 is a monolithic CMOS SPST switch. This switch is designed on an enhanced LC^2MOS process that provides low power dissipation yet gives high switching speed, low on resistance and low leakage currents.

The on resistance profile of the ADG417 is very flat over the full analog input range ensuring excellent linearity and low distortion. The part also exhibits high switching speed and high signal bandwidth. CMOS construction ensures ultralow power dissipation making the parts ideally suited for portable and battery powered instruments.

The ADG417 switch, which is turned ON with a logic low on the control input, conducts equally well in both directions when ON and has an input signal range that extends to the supplies. In the OFF condition, signal levels up to the supplies are blocked. The ADG417 exhibits break-before-make switching action for use in multiplexer applications. Inherent in the design is low charge injection for minimum transients when switching the digital input.

PRODUCT HIGHLIGHTS

- Extended Signal Range
 The ADG417 is fabricated on an enhanced LC²MOS process, giving an increased signal range that extends to the supply rails.
- 2. Ultralow Power Dissipation
- 3. Low R_{ON}
- 4. Single Supply Operation For applications where the analog signal is unipolar, the ADG417 can be operated from a single rail power supply. The part is fully specified with a single +12 V power supply and will remain functional with single supplies as low as +5 V.

REV. A

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ADG417* Product Page Quick Links

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Comparable Parts

View a parametric search of comparable parts

Documentation 🖵

Application Notes

• AN-1313: Configuring the AD5422 to Combine Output Current and Output Voltage to a Single Output Pin

Data Sheet

• ADG417: LC²MOS Precision Mini-DIP Analog Switch Data Sheet

Reference Materials

Product Selection Guide

• Switches and Multiplexers Product Selection Guide

Technical Articles

- CMOS Switches Offer High Performance in Low Power, Wideband Applications
- · Data-acquisition system uses fault protection
- Enhanced Multiplexing for MEMS Optical Cross Connects
- · Temperature monitor measures three thermal zones

Design Resources 🖵

- ADG417 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- · Symbols and Footprints

Discussions 🖵

View all ADG417 EngineerZone Discussions

Sample and Buy

Visit the product page to see pricing options

Technical Support

Submit a technical question or find your regional support number

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ADG417-SPECIFICATIONS

Dual Supply¹ (V_{DD} = +15 V ± 10%, V_{SS} = -15 V ± 10%, V_L = +5 V ± 10%, GND = 0 V, unless otherwise noted)

	B Version		T Version			
Parameter	+25°C	-40°C to +85°C	+25°C	-55°C to +125°C	Units	Test Conditions/Comments
ANALOG SWITCH				. 125 0	CIIIIS	
Analog Signal Range		V_{SS} to V_{DD}		V _{SS} to V _{DD}	V	
R _{ON}	25	133 10 1 DD	25	· 33 to • DD	Ω typ	$V_D = \pm 12.5 \text{ V}, I_S = -10 \text{ mA}$
- 01	35	45	35	45	Ω max	$V_{DD} = +13.5 \text{ V}, V_{SS} = -13.5 \text{ V}$
LEAKAGE CURRENTS						$V_{DD} = +16.5 \text{ V}, V_{SS} = -16.5 \text{ V}$
Source OFF Leakage I _S (OFF)	±0.1		± 0.1		nA typ	$V_D = \pm 15.5 \text{ V}, V_S = \mp 15.5 \text{ V};$
	±0.25	±5	±0.25	±15	nA max	Test Circuit 2
Drain OFF Leakage I _D (OFF)	±0.1		± 0.1		nA typ	$V_{\rm D} = \pm 15.5 \text{ V}, V_{\rm S} = \mp 15.5 \text{ V};$
- - · · ·	±0.25	±5	±0.25	±15	nA max	Test Circuit 2
Channel ON Leakage I _D , I _S (ON)	±0.1		± 0.1		nA typ	$V_{\rm S} = V_{\rm D} = \pm 15.5 \text{ V};$
	± 0.4	±5	± 0.4	±30	nA max	Test Circuit 3
DIGITAL INPUTS						
Input High Voltage, V _{INH}		2.4		2.4	V min	
Input Low Voltage, V _{INL}		0.8		0.8	V max	
Input Current						
I _{INL} or I _{INH}		± 0.005		± 0.005	μA typ	$V_{IN} = V_{INL}$ or V_{INH}
		±0.5		±0.5	μA max	
DYNAMIC CHARACTERISTICS ²						
t _{ON}	100		100		ns typ	$R_L = 300 \Omega$, $C_L = 35 pF$;
	160	200	145	200	ns max	$V_s = \pm 10 V$; Test Circuit 4
t _{OFF}	60		60		ns typ	$R_L = 300 \Omega$, $C_L = 35 pF$;
	100	150	100	150	ns max	$V_s = \pm 10 V$; Test Circuit 4
Charge Injection	7		7		pC typ	$V_{\rm S}=0~V,~R_{\rm L}=0~\Omega,$
						$C_L = 10 \text{ nF}$; Test Circuit 5
OFF Isolation	80		80		dB typ	$R_L = 50 \Omega$, f = 1 MHz;
						Test Circuit 6
C _s (OFF)	6		6		pF typ	
C _D (OFF)	6		6		pF typ	
$C_D, C_S (ON)$	55		55		pF typ	
POWER REQUIREMENTS						V_{DD} = +16.5 V, V_{SS} = -16.5 V
I _{DD}	0.0001		0.0001		μA typ	$V_{IN} = 0 V \text{ or } 5 V$
	1	2.5	1	2.5	μA max	
I _{SS}	0.0001		0.0001		μA typ	
	1	2.5	1	2.5	μA max	
I_L	0.0001		0.0001		μA typ	$V_{L} = +5.5 V$
	1	2.5	1	2.5	μA max	

NOTES

¹Temperature ranges are as follows: B Version: -40 °C to +85 °C; T Version: -55 °C to +125 °C.

²Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

Single Supply¹ ($V_{DD} = +12 V \pm 10\%$, $V_{SS} = 0 V$, $V_L = +5 V \pm 10\%$, GND = 0 V, unless otherwise noted)

	В	Version	T Ve	ersion		
		-40°C to		-55°C to		
Parameter	+25°C	+85°C	+25°C	+125°C	Units	Test Conditions/Comments
ANALOG SWITCH						
Analog Signal Range		0 to V_{DD}		0 to V_{DD}	V	
R _{ON}	40		40		Ω typ	$V_D = +3 V$, +8.5 V, $I_S = -10 mA$
		60		70	Ω max	$V_{DD} = +10.8 V$
LEAKAGE CURRENT						$V_{DD} = +13.2 \text{ V}$
Source OFF Leakage I _S (OFF)	±0.1		±0.1		nA typ	$V_{\rm D} = 12.2 \text{ V/1 V}, V_{\rm S} = 1 \text{ V/12.2 V};$
	±0.25	±5	±0.25	±15	nA max	Test Circuit 2
Drain OFF Leakage I _D (OFF)	±0.1		±0.1		nA typ	$V_{\rm D} = 12.2 \text{ V/1 V}, V_{\rm S} = 1 \text{ V/12.2 V};$
	±0.25	±5	±0.25	±15	nA max	Test Circuit 2
Channel ON Leakage I _D , I _S (ON)	±0.1		±0.1		nA typ	$V_{\rm S} = V_{\rm D} = 12.2 \text{ V/1 V};$
	± 0.4	± 5	±0.4	±30	nA max	Test Circuit 3
DIGITAL INPUTS						
Input High Voltage, V _{INH}		2.4		2.4	V min	
Input Low Voltage, V _{INL}		0.8		0.8	V max	
Input Current						
I _{INL} or I _{INH}		± 0.005		± 0.005	μA typ	$V_{IN} = V_{INL}$ or V_{INH}
		± 0.5		±0.5	μA max	
DYNAMIC CHARACTERISTICS ²						
t _{on}	180	250	180	250	ns max	$R_L = 300 \Omega$, $C_L = 35 pF$;
						$V_s = +8 V$; Test Circuit 4
t _{OFF}	85	110	85	110	ns max	$R_L = 300 \Omega, C_L = 35 pF;$
						$V_s = +8 V$; Test Circuit 4
Charge Injection	11		11		pC typ	$\mathbf{V}_{\mathrm{S}}=0\ \mathrm{V},\ \mathbf{R}_{\mathrm{S}}=0\ \Omega,$
						$C_L = 10 \text{ nF}$; Test Circuit 5
OFF Isolation	80		80		dB typ	$R_L = 50 \Omega$, f = 1 MHz;
	10		10			Test Circuit 6
C_{s} (OFF)	13		13		pF typ	
$C_{\rm D}$ (OFF)	13		13		pF typ	
$C_{\rm D}, C_{\rm S} ({\rm ON})$	65		65		pF typ	
POWER REQUIREMENTS						$V_{DD} = +13.2 V$
I _{DD}	0.0001		0.0001		μA typ	$V_{IN} = 0 V \text{ or } 5 V$
-	1	2.5	1	2.5	μA max	
IL	0.0001		0.0001		μA typ	$V_{L} = +5.5 V$
	1	2.5	1	2.5	μA max	

NOTES

¹Temperature ranges are as follows: B Version: -40 °C to +85 °C; T Version: -55 °C to +125 °C.

²Guaranteed by design, not subject to production test.

Specifications subject to change without notice.

Table I. Truth Table

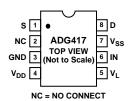
Logic	Switch Condition		
0	ON		
1	OFF		

ORDERING GUIDE

Model	Temperature Range	Package Options*	
ADG417BN	-40°C to +85°C	N-8	
ADG417BR	-40°C to +85°C	SO-8	

*N = Plastic DIP, SO = 0.15" Small Outline IC (SOIC).

PIN CONFIGURATION DIP/SOIC



ADG417

ABSOLUTE MAXIMUM RATINGS¹

$(T_A = +25^{\circ}C \text{ unless otherwise noted})$
V_{DD} to V_{SS}
V_{DD} to GND0.3 V to +25 V
V_{SS} to GND+0.3 V to -25 V
V_L to GND0.3 V to V_{DD} + 0.3 V
Analog, Digital Inputs ² $V_{SS} - 2 V$ to $V_{DD} + 2 V$
or 30 mA, Whichever Occurs First
Continuous Current, S or D 30 mA
Peak Current, S or D 100 mA
(Pulsed at 1 ms, 10% Duty Cycle Max)
Operating Temperature Range
Industrial (B Version)40°C to +85°C
Extended (T Version)55°C to +125°C
Storage Temperature Range65°C to +150°C
Junction Temperature 150°C

Plastic Package, Power Dissipation
θ_{JA} , Thermal Impedance
Lead Temperature, Soldering (10 sec) +260°C
SOIC Package, Power Dissipation
θ_{JA} , Thermal Impedance
Lead Temperature, Soldering
Vapor Phase (60 sec) +215°C
Infrared (15 sec) +220°C

NOTES

¹Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Only one absolute maximum rating may be applied at any one time.

²Overvoltages at IN, S or D will be clamped by internal diodes. Current should be limited to the maximum ratings given.

CAUTION.

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADG417 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.



TERMINOLOGY

V_{DD} Most positive power supply potential. C_S (OFF)"OFF" switch source capacitance. V_{SS} Most negative power supply potential in dual supplies. In single supply applications, it may be connected to GND. C_D (OFF)"OFF" switch drain capacitance.	TERMINOLOGY	Y	$V_{\rm D}$ (V _S)	Analog voltage on terminals D, S.
supplies. In single supply applications, it may be connected to GND. $C_D, C_S (ON)$ "ON" switch capacitance.	V _{DD}	Most positive power supply potential.	,	
may be connected to GND. $C_D, C_S(ON)$ On swhen capacitance.	V _{SS}		C _D (OFF)	"OFF" switch drain capacitance.
t Delay between applying the digital control			C_D , $C_S(ON)$	-
V_L Logic power supply (+5 V). Logic power supply (+5 V). input and the output switching on.	V_L	-	t _{ON}	Delay between applying the digital control
GND Ground (0 V) reference. Lore Delay between applying the digital control			t _{OFF}	
S Source terminal. May be an input or an input and the output switching off.	S	• •		
output. V _{INL} Maximum input voltage for logic "0."	D	-		
D Drain terminal. May be an input or an V _{INH} Minimum input voltage for logic "1."	D	• •	V _{INH}	Minimum input voltage for logic "1."
output. I_{INL} (I_{INH}) Input current of the digital input.		*	I_{INL} (I_{INH})	Input current of the digital input.
IN Logic control input. Charge Injection A measure of the glitch impulse transferred			Charge Injection	A measure of the glitch impulse transferred
R _{ON} Ohmic resistance between D and S. from the digital input to the analog output	R _{ON}	Ohmic resistance between D and S.		from the digital input to the analog output
I _S (OFF) Source leakage current with the switch during switching.	I _S (OFF)	Source leakage current with the switch		
"OFF." Off Isolation A measure of unwanted signal coupling		"OFF."	Off Isolation	A measure of unwanted signal coupling
I _D (OFF) Drain leakage current with the switch through an "OFF" channel.	I _D (OFF)	Drain leakage current with the switch		through an "OFF" channel.
"OFF." I _{DD} Positive supply current.	_	"OFF."	I _{DD}	Positive supply current.
I_D, I_S (ON) Channel leakage current with the switch I_{SS} Negative supply current.	$I_D, I_S(ON)$	•		
"ON." I _L Logic supply current.		"ON."	I_L	Logic supply current.

Typical Performance Characteristics–ADG417

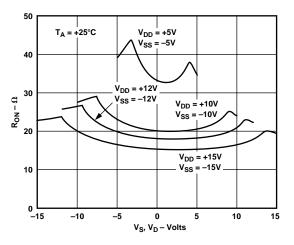


Figure 1. R_{ON} as a Function of V_D (V_S): Dual Supply Voltage

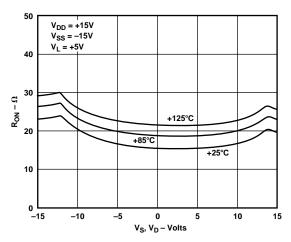


Figure 2. R_{ON} as a Function of V_D (V_S) for Different Temperatures

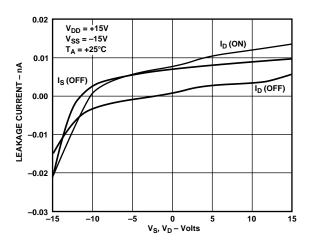


Figure 3. Leakage Currents as a Function of V_S (V_D)

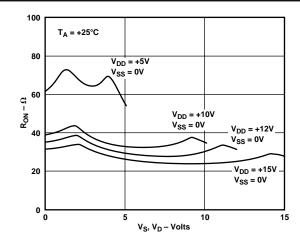


Figure 4. R_{ON} as a Function of V_D (V_S): Single Supply Voltage

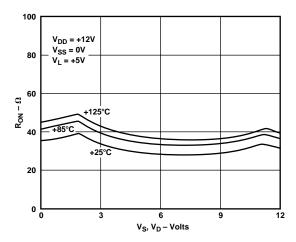


Figure 5. R_{ON} as a Function of V_D (V_S) for Different Temperatures

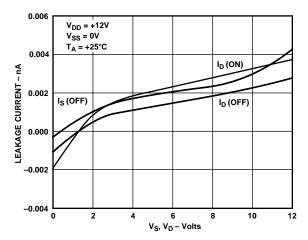


Figure 6. Leakage Currents as a Function of $V_S(V_D)$

ADG417

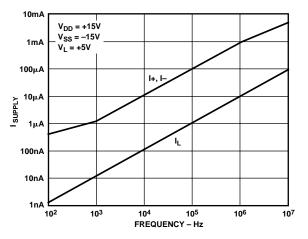


Figure 7. Supply Current vs. Input Switching Frequency

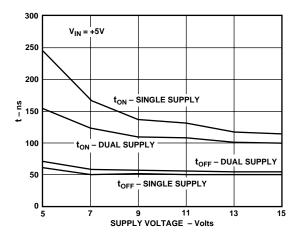
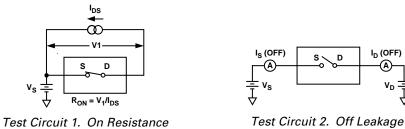


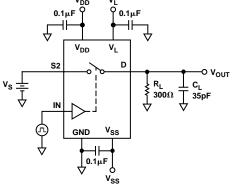
Figure 8. Switching Time vs. Power Supply

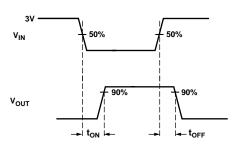
Test Circuits

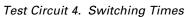


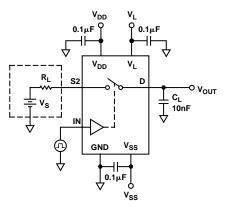
 $\begin{array}{c|c} & S & D & I_D (ON) \\ \hline \hline \hline \hline \hline \hline \hline V_S & V_D & \hline \hline \hline \hline \end{array}$

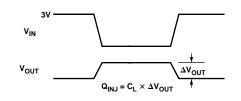
Test Circuit 3. On Leakage



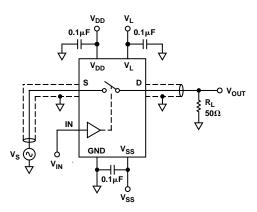








Test Circuit 5. Charge Injection

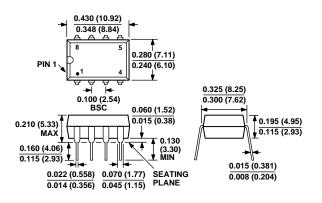


Test Circuit 6. Off Isolation

OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

8-Lead Plastic DIP (N-8)



8-Lead SOIC (SO-8) (Narrow Body)

